

# DSC8004

## Silicon NPN epitaxial planar type

For low frequency output amplification  
Complementary to DSA8004  
DSC7004 in MT-2 through hole type package

### ■ Features

- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

### ■ Packaging

DSC8004×0A Radial type : 2000 pcs / carton

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	60	V
Collector-emitter voltage (Base open)	$V_{CEO}$	50	V
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V
Collector current	$I_C$	2	A
Peak collector current	$I_{CP}$	3	A
Collector power dissipation *	$P_C$	1	W
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*: Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu\text{A}, I_E = 0$	60			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 1 \text{ mA}, I_B = 0$	50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_E = 0$			0.1	$\mu\text{A}$
Forward current transfer ratio *1	$h_{FE1}$ *2	$V_{CE} = 2 \text{ V}, I_C = 200 \text{ mA}$	120		340	—
	$h_{FE2}$	$V_{CE} = 2 \text{ V}, I_C = 1 \text{ A}$	80			
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = 1 \text{ A}, I_B = 50 \text{ mA}$		0.15	0.3	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = 1 \text{ A}, I_B = 50 \text{ mA}$		0.9	1.2	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_C = 50 \text{ mA}$		120		MHz
Collector output capacitance (Common base, input open circuited)	$C_{ob}$	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		22	35	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

\*2: Rank classification

Code	R	S	0
Rank	R	S	No-rank
$h_{FE1}$	120 to 240	170 to 340	120 to 340
Marking Symbol	5BR	5BS	5B

Product of no-rank is not classified and have no marking symbol for rank.

### ■ Package

#### • Code

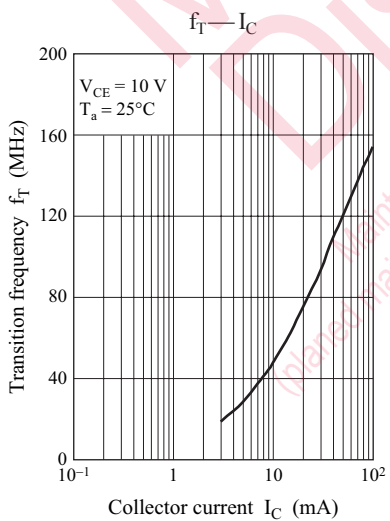
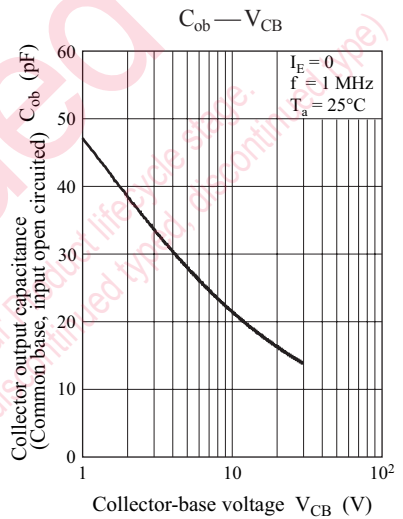
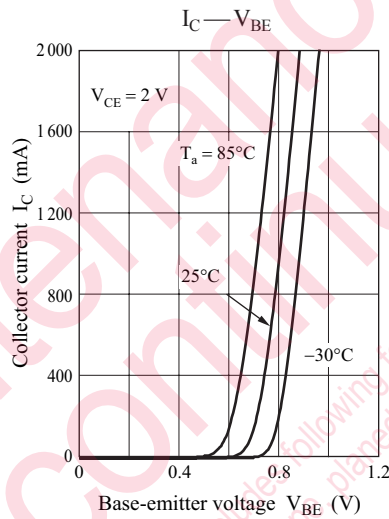
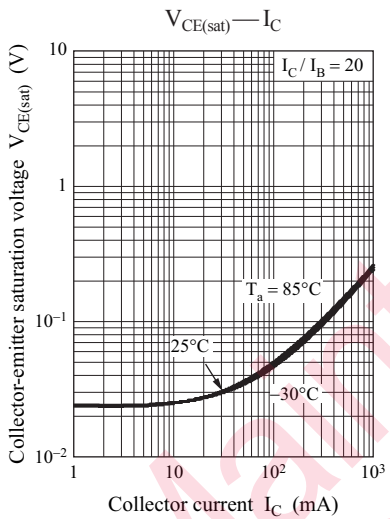
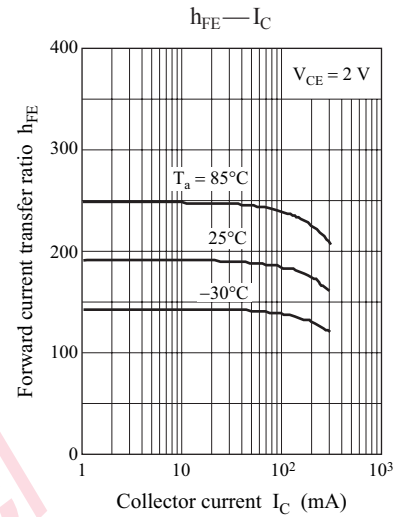
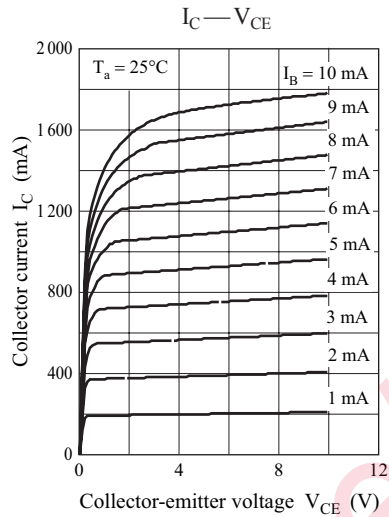
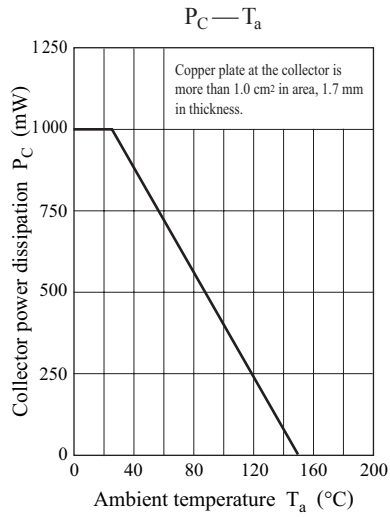
MT-2-A2-B

Package dimension clicks here.→

#### • Pin Name

1. Emitter
2. Collector
3. Base

### ■ Marking Symbol: 5B



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